

SEMICONDUCTOR DEVICE MANUFACTURING METHOD, SEMICONDUCTOR DEVICE, AND WIRE BONDING APPARATUS

ABSTRACT

A semiconductor device manufacturing method includes: raising and moving a bonding tool 40, while paying out a wire 42, in a direction from a second toward a first bonding point to form in the wire 42 a cut portion 92 bent in the vicinity of the second bonding point; lowering and moving the tip of the bonding tool 40 to the cut portion 92; lowering the bonding tool 40 vertically to thin the cut portion 92; raising the bonding tool 40 while paying out the wire 42; and moving the bonding tool 40 in a direction away from the first and second bonding points and along a wire direction connecting the first and second bonding points and then cutting the wire at the cut portion 92 to form a wire tail 43. This allows the length of the wire tail to be adjusted easily and efficiently to be constant.

Fig. 3